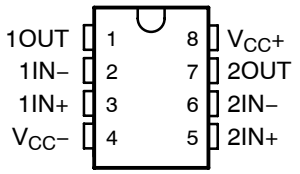
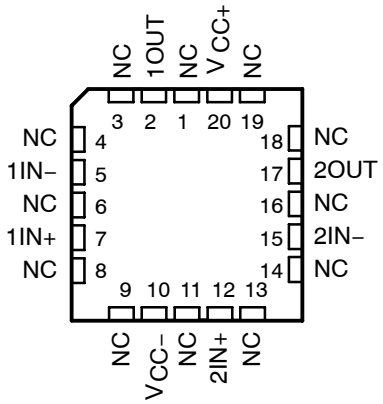
SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

- **Short-Circuit Protection**
- **Wide Common-Mode and Differential Voltage Ranges**
- **No Frequency Compensation Required**
- **Low Power Consumption**
- **No Latch-Up**
- **Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558**

MC1458 . . . D, P, OR PS PACKAGE
MC1558 . . . JG PACKAGE
(TOP VIEW)



MC1558 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The MC1458 and MC1558 are dual general-purpose operational amplifiers, with each half electrically similar to the μA741, except that offset null capability is not provided.

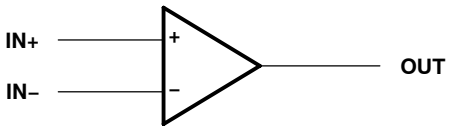
The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.

ORDERING INFORMATION

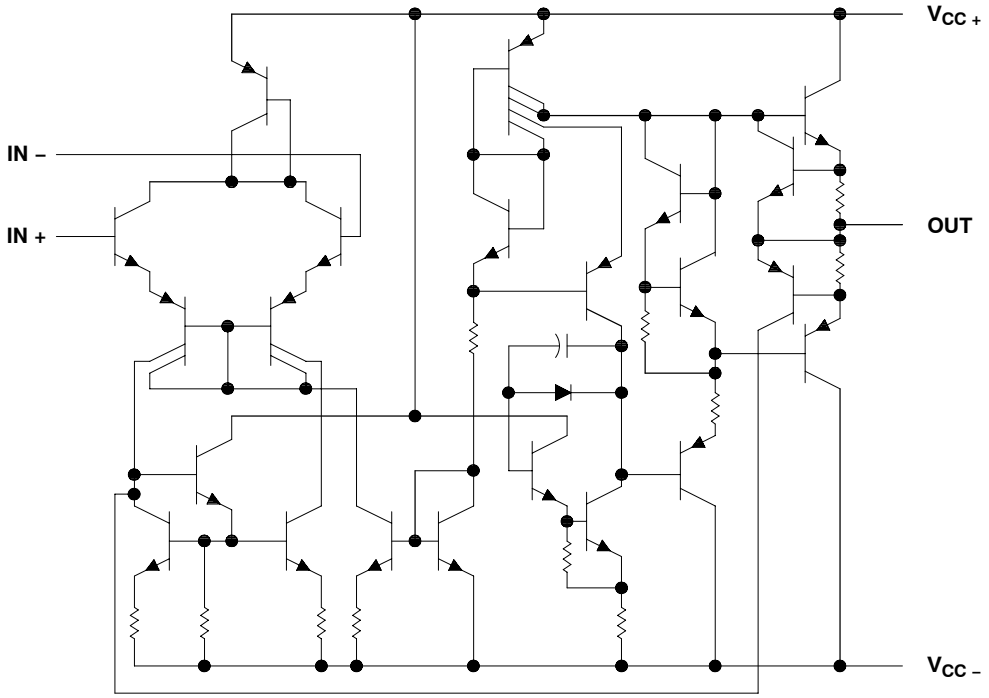
T_A	V_{IO}max AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (P)	Tube	MC1458P	MC1458P
		SOIC (D)	Tube	MC1458D	MC1458
			Tape and reel	MC1458DR	
		SOP (PS)	Tape and reel	MC1458PSR	M1458
–55°C to 125°C	5 mV	CDIP (JG)	Tube	MC1558JG	MC1558JG
		CDIP (JGB)	Tube	MC1558JGB	MC1558JGB
		LCCC (FK)	Tube	MC1558FK	MC1558FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each amplifier)



schematic (each amplifier)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (see Note 1): MC1458 . . . . . 18 V
MC1558 . . . . . 22 V
Supply voltage, V_{CC-} (see Note 1): MC1458 . . . . . –18 V
MC1558 . . . . . –22 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±30 V
Input voltage, V_I (either input, see Notes 1 and 3) . . . . . ±15 V
Duration of output short circuit (see Note 4) . . . . . Unlimited
Operating virtual junction temperature, T_J . . . . . 150°C
Package thermal impedance, θ_{JA} (see Notes 5 and 6): D package . . . . . 97°C/W
P package . . . . . 85°C/W
PS package . . . . . 95°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8): FK package . . . . . 5.61°C/W
JG package . . . . . 14.5°C/W
Case temperature for 60 seconds: FK package . . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: JG package . . . . . 300°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: D, P, or PS package . . . . . 260°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:
1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
2. Differential voltages are at IN+ with respect to IN–.
3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
6. The package thermal impedance is calculated in accordance with JESD 51-7.
7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC}, and T_C. The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

			MIN	MAX	UNIT
$V_{CC\pm}$	Supply voltage		±5	±15	V
T_A	Operating free-air temperature range	MC1458	0	70	°C
		MC1558	–55	125	

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ±15 V

PARAMETER		TEST CONDITIONS†		MC1458			MC1558			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0	25°C		1	6		1	5	mV
			Full range			7.5			6	
I_{IO}	Input offset current	V_O = 0	25°C		20	200		20	200	nA
			Full range			300			500	
I_{IB}	Input bias current	V_O = 0	25°C		80	500		80	500	nA
			Full range			800			1500	
V_{ICR}	Common-mode input voltage range		25°C	±12	±13		±12	±13		V
			Full range	±12			±12			
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ	25°C	±12	±14		±12	±14		V
		R_L ≥ 10 kΩ	Full range	±12			±11			
		R_L = 2 kΩ	25°C	±10	±13		±10	±13		
		R_L ≥ 2 kΩ	Full range	±10			±10			
A_{VD}	Large-signal differential voltage amplification	R_L ≥ 2 kΩ, V_O = ±10 V	25°C	20	200		50	200		V/mV
			Full range	15			25			
B_{OM}	Maximum-output-swing bandwidth (closed loop)	R_L = 2 kΩ, V_O ≥ ±10 V, A_{VD} = 1, THD ≥ 5%	25°C		14			14		kHz
B_1	Unity-gain bandwidth		25°C		1			1		MHz
ϕm	Phase margin	A_{VD} = 1	25°C		65			65		deg
	Gain margin		25°C		11			11		dB
r_i	Input resistance		25°C	0.3	2		0.3*	2		MΩ
r_o	Output resistance	V_O = 0, See Note 9	25°C		75			75		Ω
C_i	Input capacitance		25°C		1.4			1.4		pF
z_{ic}	Common-mode input impedance	f = 20 Hz	25°C		200			200		MΩ
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR} min, V_O = 0	25°C	70	90		70	90		dB
			Full range	70			70			
k_{SVS}	Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	V_{CC} = ±9 V to ±15 V, V_O = 0	25°C		30	150		30	150	μV/V
			Full range			150			150	
V_n	Equivalent input noise voltage (closed loop)	A_{VD} = 100, R_S = 0, f = 1 kHz, BW = 1 Hz	25°C		45			45		nV/√Hz
I_{OS}	Short-circuit output current		25°C		±25	±40		±25	±40	mA
I_{CC}	Supply current (both amplifiers)	V_O = 0, No load	25°C		3.4	5.6		3.4	5	mA
			Full range			6.6			6.6	
P_D	Total power dissipation (both amplifiers)	V_O = 0, No load	25°C		100	170		100	150	mW
			Full range			200			200	
V_{O1}/V_{O2}	Crosstalk attenuation		25°C		120			120		dB

*On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is −55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.

operating characteristics, $V_{CC\pm}$ = ±15 V, C_L = 100 pF, T_A = 25°C (see Figure 1)

PARAMETER		TEST CONDITIONS		MC1458			MC1558			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_r	Rise time	V_I = 20 mV,	R_L = 2 kΩ,		0.3			0.3		μs
	Overshoot factor	V_I = 20 mV,	R_L = 2 kΩ		5			5		%
SR	Slew rate at unity gain	V_I = 10 V,	R_L = 2 kΩ		0.5			0.5		V/μs

PARAMETER MEASUREMENT INFORMATION

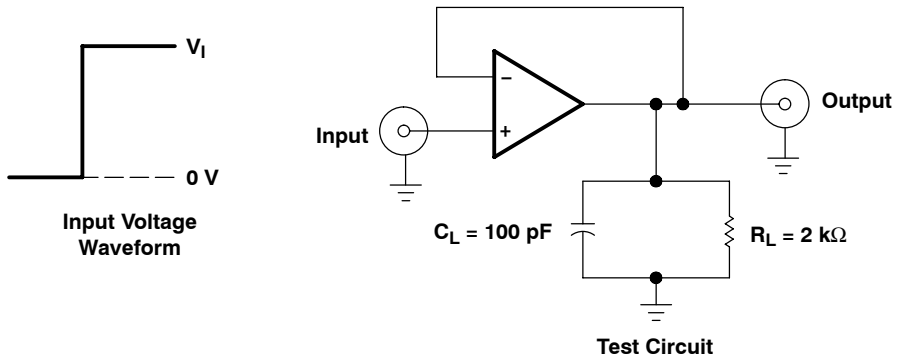


Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9760301Q2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9760301Q2A MC1558FKB
5962-9760301QPA	Active	Production	CDIP (JG) | 8	50 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	9760301QPA MC1558
MC1458DR	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458
MC1458DR.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458
MC1458DR.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458
MC1458DRG4	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	-	Call TI	Call TI	0 to 70	
MC1458P	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	MC1458P
MC1458P.A	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	MC1458P
MC1458P.B	Active	Production	PDIP (P) | 8	50 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	MC1458P
MC1458PE4	Active	Production	PDIP (P) | 8	50 | TUBE	-	Call TI	Call TI	0 to 70	
MC1458PSR	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	M1458
MC1458PSR.A	Active	Production	SO (PS) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	M1458
MC1558FKB	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9760301Q2A MC1558FKB
MC1558FKB.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9760301Q2A MC1558FKB
MC1558JG	Active	Production	CDIP (JG) | 8	50 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	MC1558JG
MC1558JG.A	Active	Production	CDIP (JG) | 8	50 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	MC1558JG
MC1558JGB	Active	Production	CDIP (JG) | 8	50 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	9760301QPA MC1558
MC1558JGB.A	Active	Production	CDIP (JG) | 8	50 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	9760301QPA MC1558

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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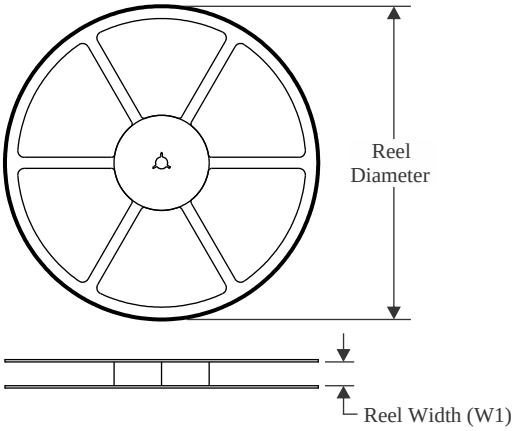
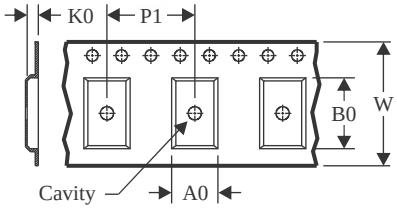
TAPE AND REEL INFORMATION

REEL DIMENSIONS

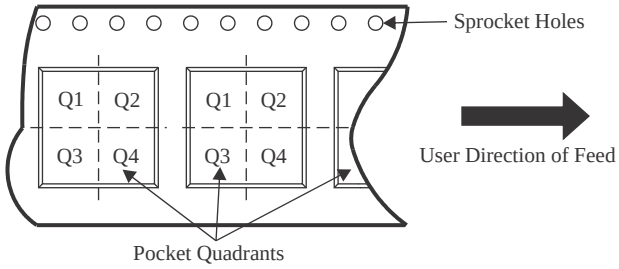


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

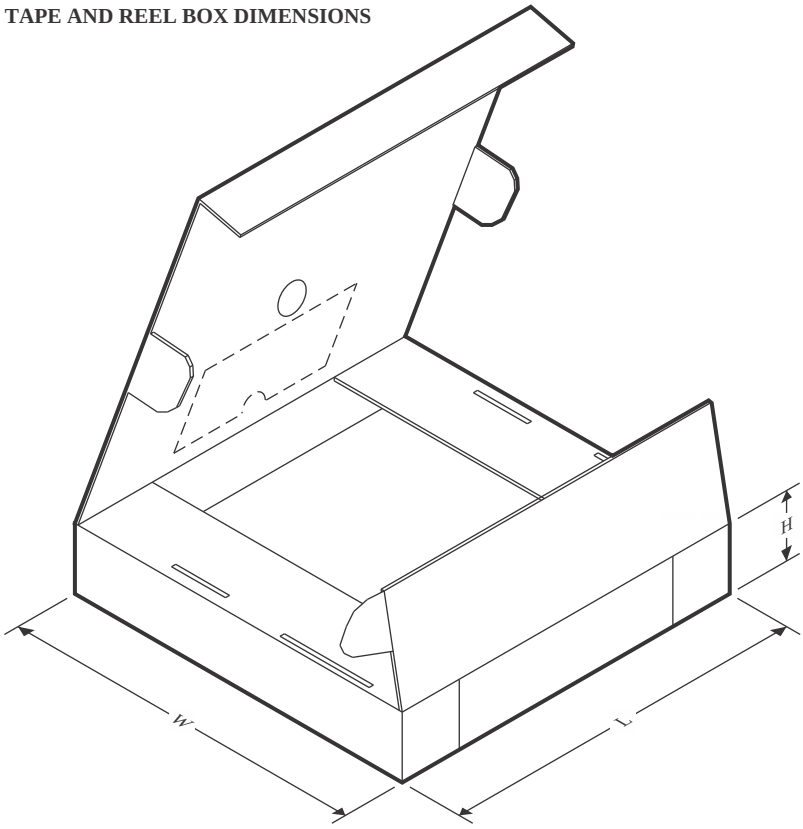
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458PSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1

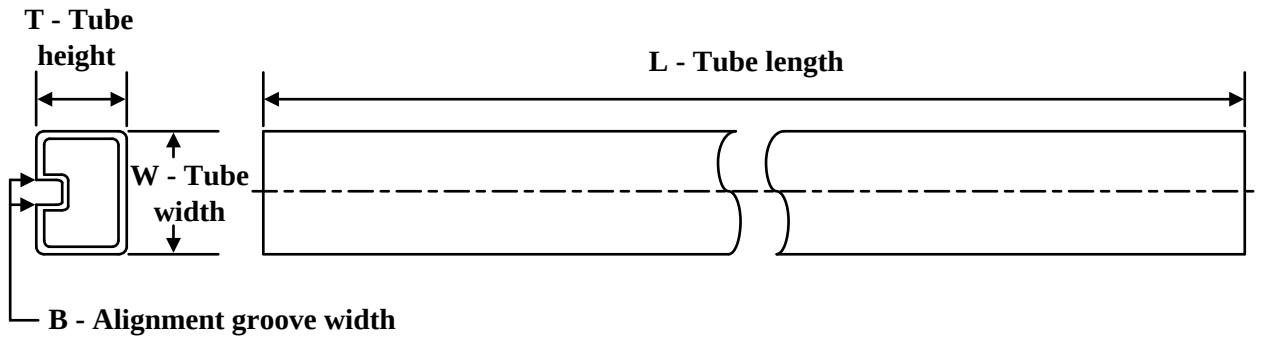
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC1458DR	SOIC	D	8	2500	340.5	338.1	20.6
MC1458DR	SOIC	D	8	2500	340.5	336.1	25.0
MC1458DR	SOIC	D	8	2500	353.0	353.0	32.0
MC1458DR	SOIC	D	8	2500	353.0	353.0	32.0
MC1458PSR	SO	PS	8	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

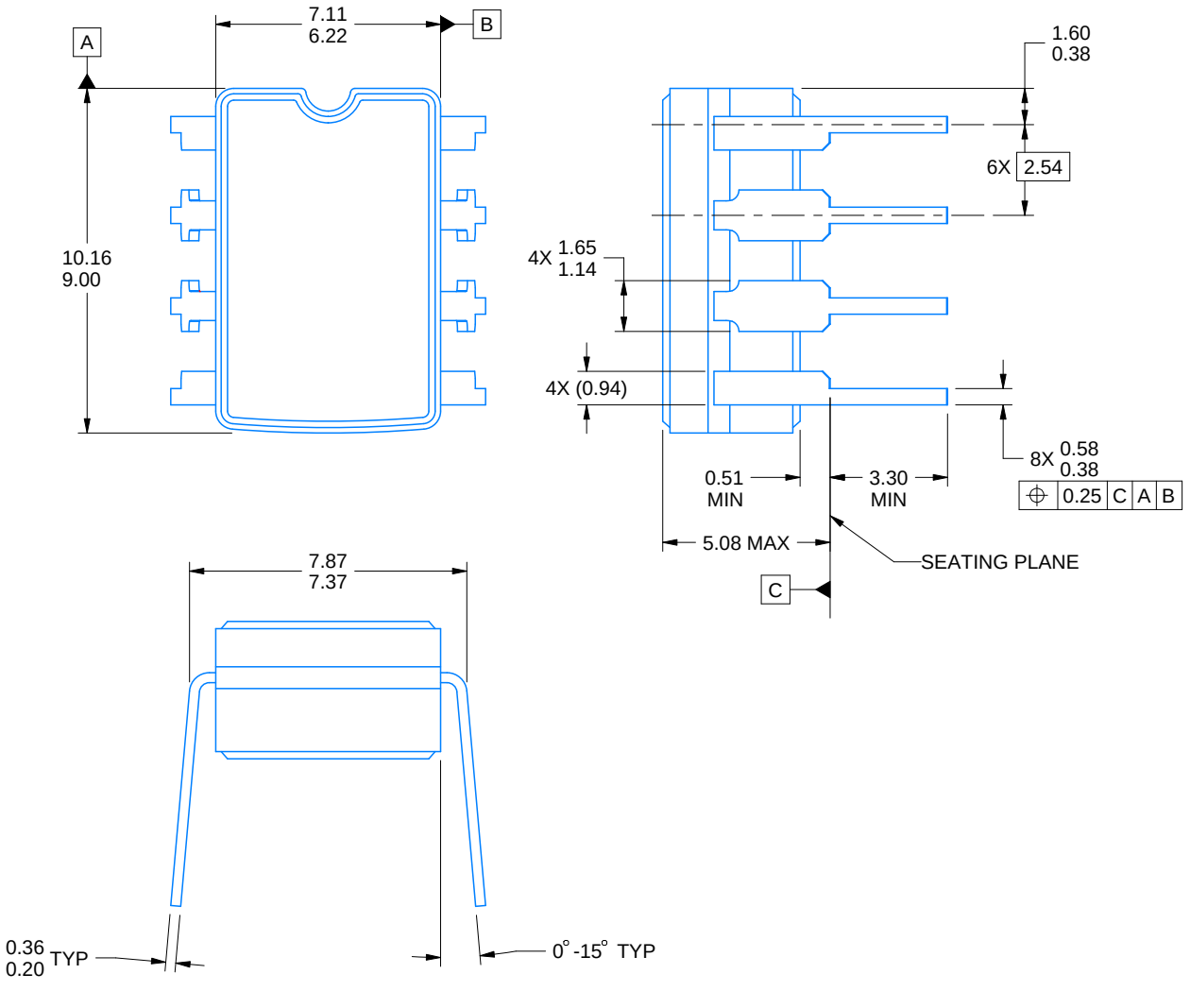
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9760301Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
MC1458P	P	PDIP	8	50	506	13.97	11230	4.32
MC1458P	P	PDIP	8	50	506	13.97	11230	4.32
MC1458P.A	P	PDIP	8	50	506	13.97	11230	4.32
MC1458P.A	P	PDIP	8	50	506	13.97	11230	4.32
MC1458P.B	P	PDIP	8	50	506	13.97	11230	4.32
MC1458P.B	P	PDIP	8	50	506	13.97	11230	4.32
MC1558FKB	FK	LCCC	20	55	506.98	12.06	2030	NA
MC1558FKB.A	FK	LCCC	20	55	506.98	12.06	2030	NA

PACKAGE OUTLINE

JG0008A

CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE



4230036/A 09/2023

NOTES:

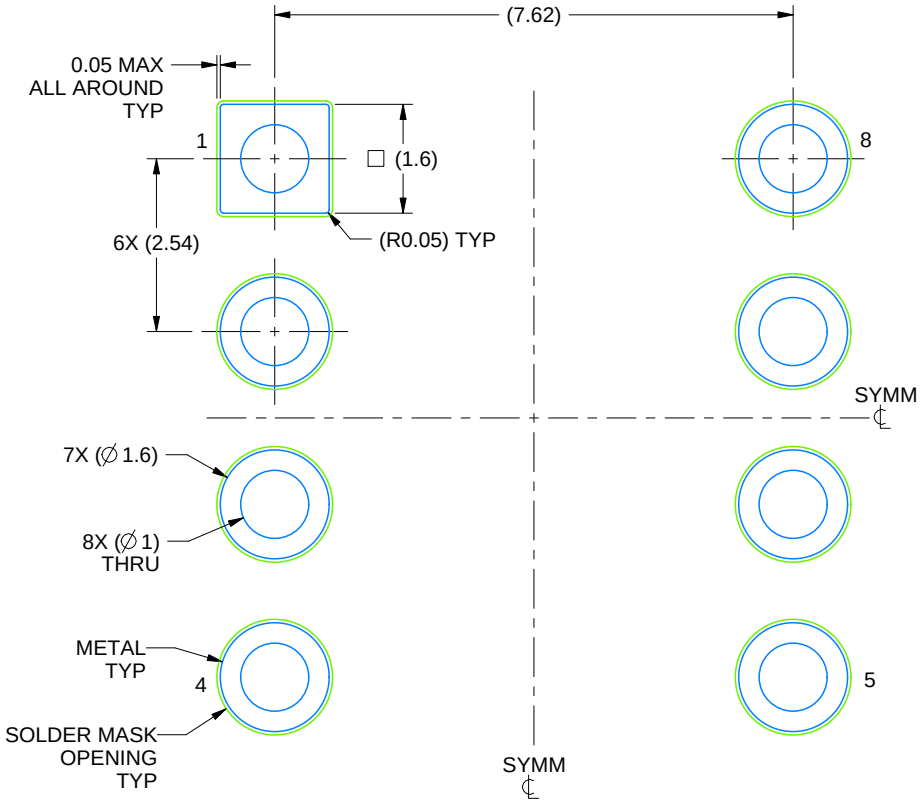
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package can be hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification.
5. Falls within MIL STD 1835 GDIP1-T8

EXAMPLE BOARD LAYOUT

JG0008A

CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE



LAND PATTERN EXAMPLE
NON SOLDER MASK DEFINED
SCALE: 9X

4230036/A 09/2023

GENERIC PACKAGE VIEW

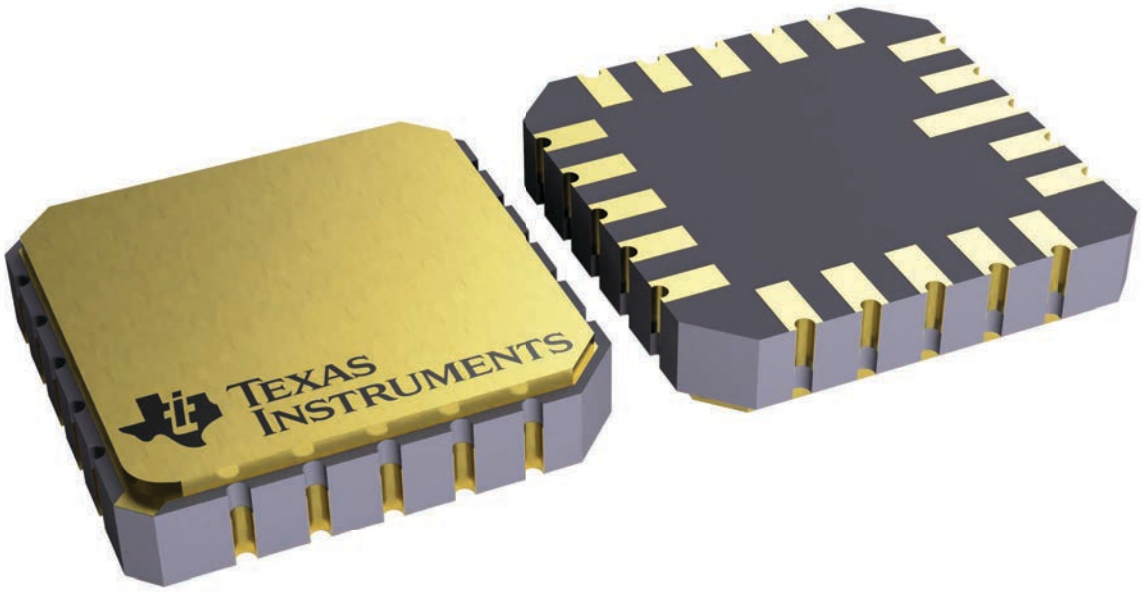
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



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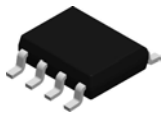
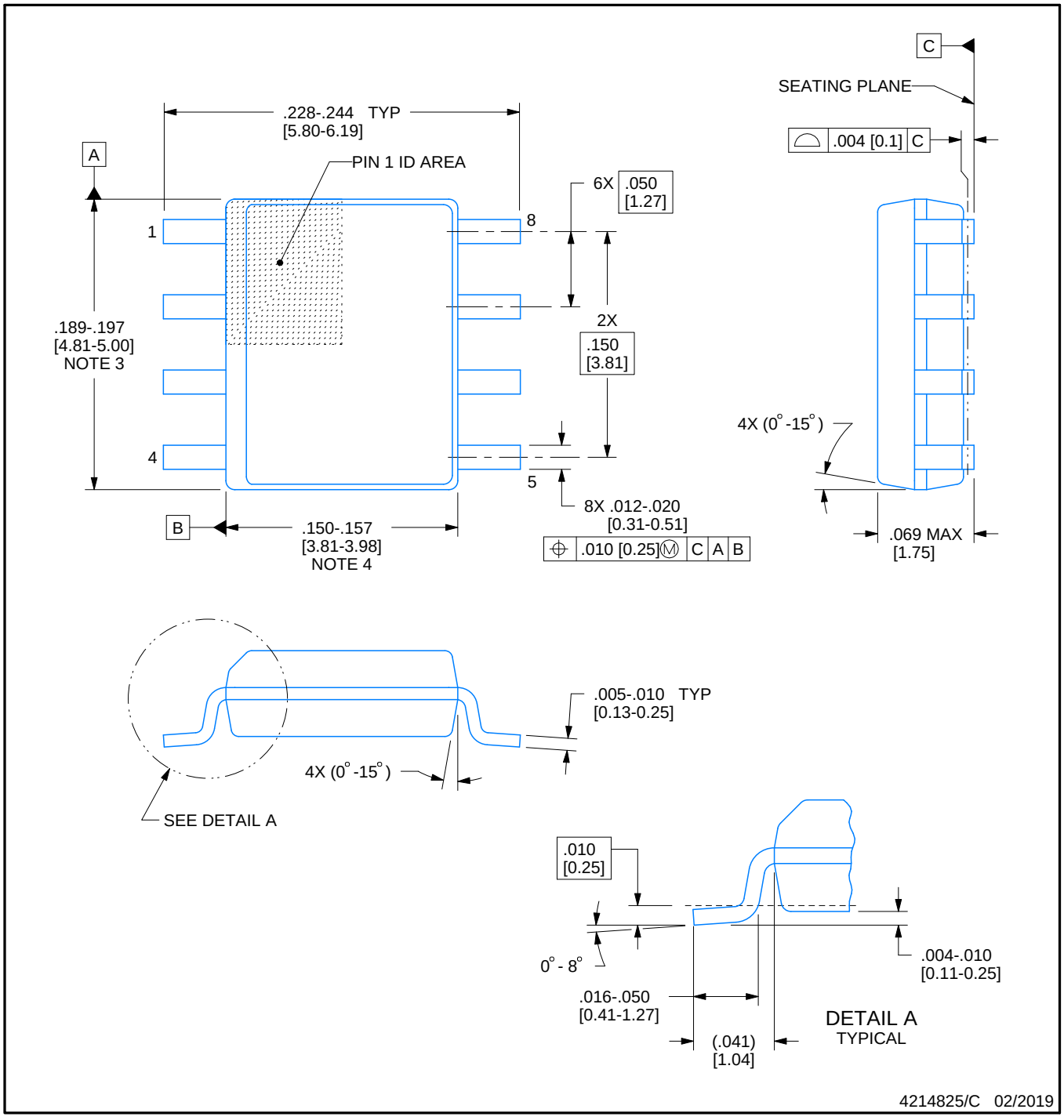


PACKAGE OUTLINE

D0008A

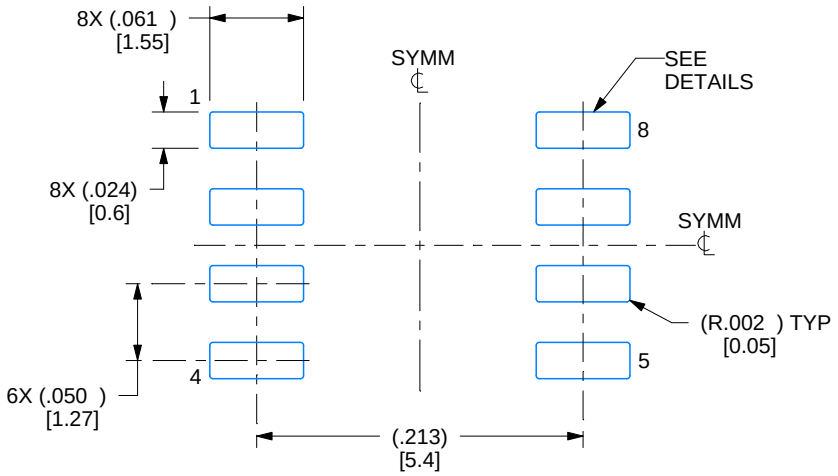
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

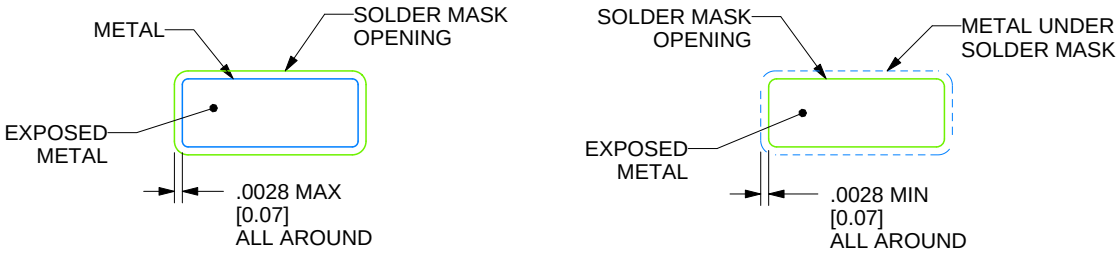


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

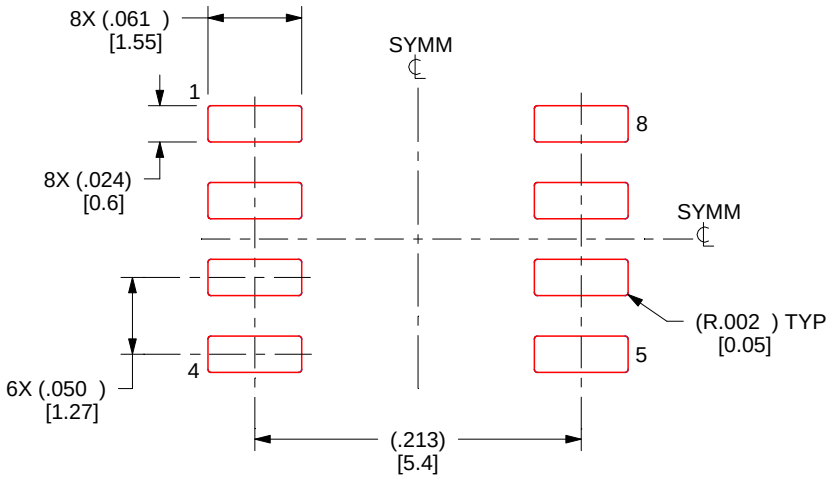
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

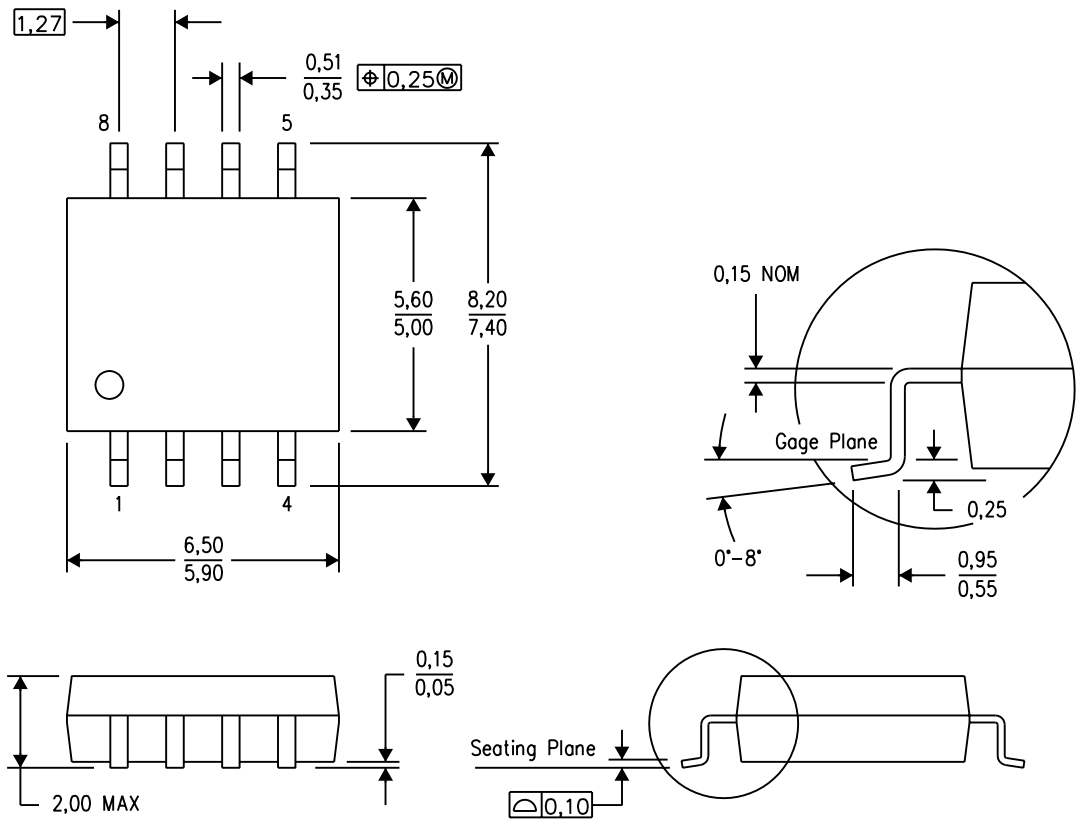
4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

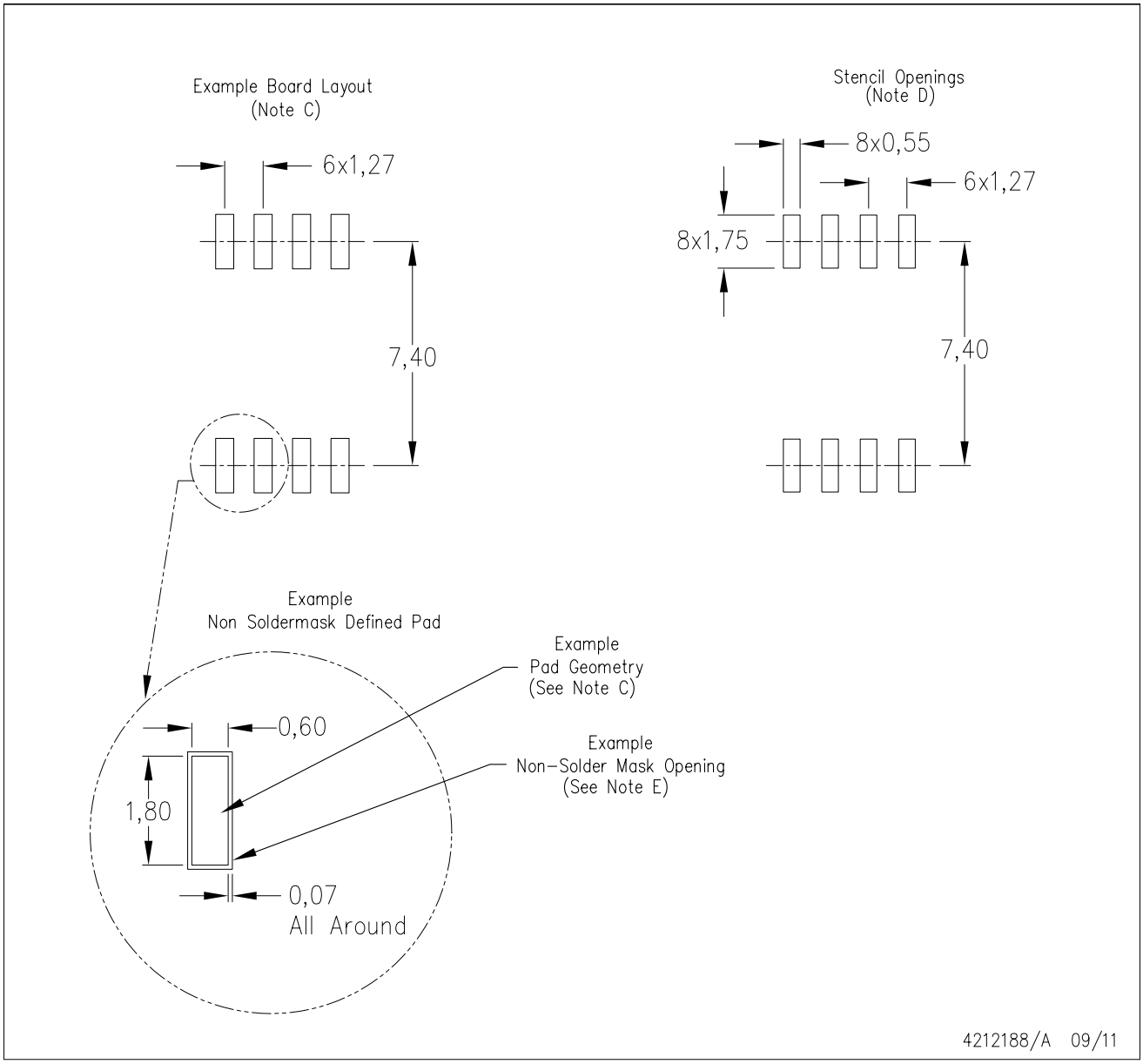
PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



4040063/C 03/03

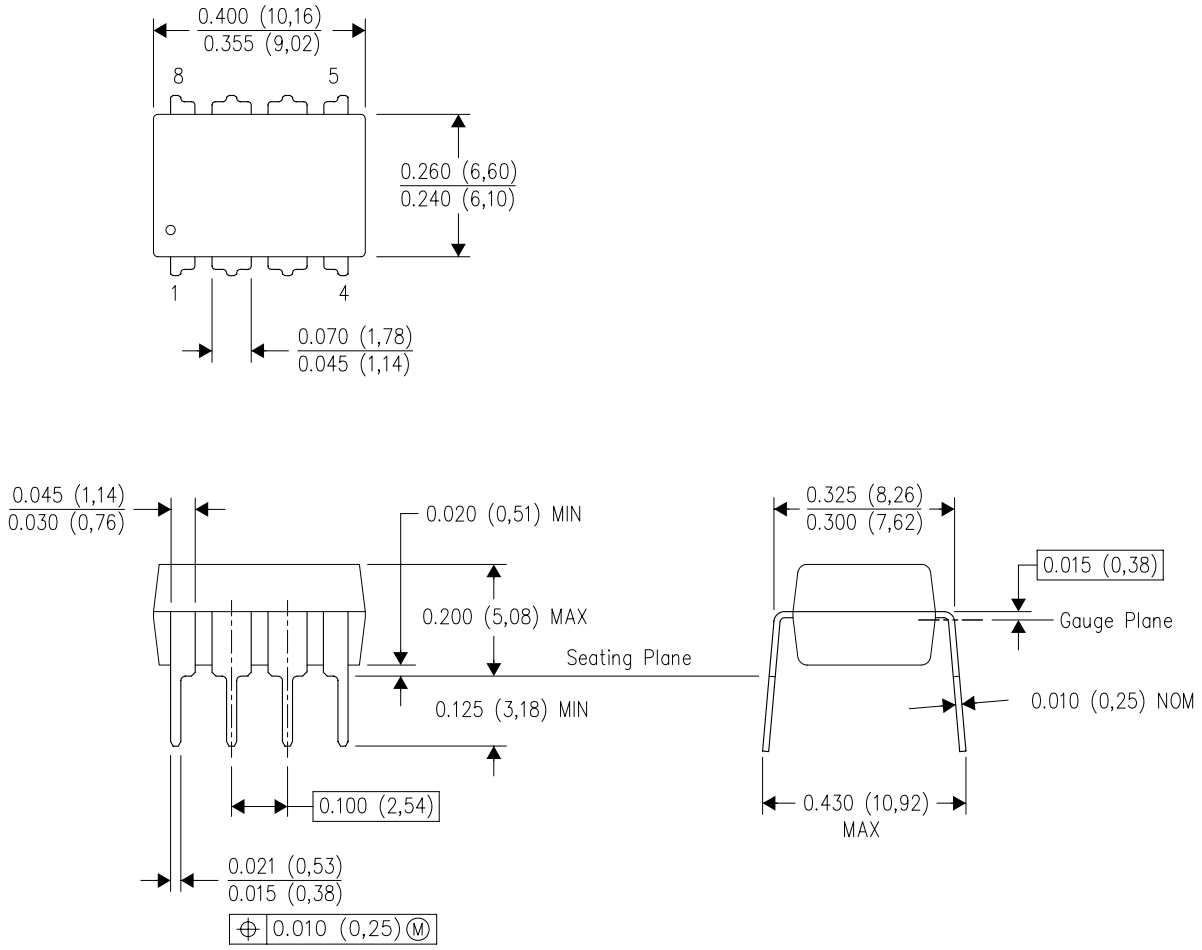
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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